

Parameter	Symbol	Rating	Units	
Load Voltage	VL	80	V	
Load Current	lL .	0.08	Α	
On-Resistance	Ron	35	Ω	
I/O Breakdown Voltage	V/IO	2500	Vrms	





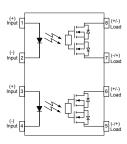




E534710



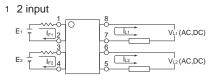
SOP-8

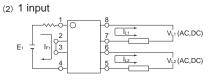


1,3. LED Anode

2,4. LED Cathode 5,6. Drain (MOS FET)

7,8. Drain (MOS FET)





APSEMI PhotoRelays

APSEMI Photorelays are the most reliable, technically advanced logic-to-power interface devices. Their basic function is to take a low current signal from a microprocessor to control the switching of both AC and DC loads, while providing an isolation barrier between logic and power. While this function is common to all relays, Photorelays provide distinct advantages over their mechanical counterparts including:

- Long life (No limit on mechanical and electrical
- lifetime)Bounce-free switching
- · Higher speed and high frequency switching
- Higher sensitivity (less power consumption)
- Immunity to EMI or RFI

- No have voltaic arc, bounce, and noise More
- resistant to vibration and impact AC or DC load
- switching
- Small package size

Applications

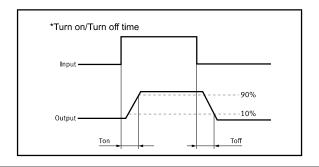
These advantages make APSEI Photorelays the ideal choice for:

- Telecom/Datacom switching
- Multiplexers
- Meter reading systems
- Data acquisition
- Medical equipment
- Battery monitoring
- I/O Sub-Systems

- Robotics
- Aerospace
- Home/Safety security systems
- Process Control
- Energy Management
- Reed Relay EMR Replacement
- Programmable Controllers

TPYES

Output Rating		Doolsons	Part No.	Packing Overtity		
Category	Load Voltage	Load Current	Package	Part No.	Packing Quantity	
AC/DC	80V	0.08A	SOP-8	APW215LCS	2000pcs /reel	





Absolute Maximum Ratings (Ta = 25°C)

	Item	Symbol	Va l ue	Units	Note
	Continuous LED Current	lF	50	mA	
Input	Peak LED Current	I FP	1000	mA	f=100Hz, duty=1%
·	LED Reverse Voltage	VR	5	V	
	Input Power Dissipation	Pin	75	mW	
Output	Load Voltage	VL	80	V(AC peak or DC)	
	Load Current	ĬL.	0.08	А	
	Peak Load Current	Peak	0.20	А	100ms(1 pulse)
	Output Power Dissipation	Pout	350	mW	
Total Power	Dissipation	Р⊤	450	mW	
I/O Breakdov	vn Vo l tage	V _{I/O}	2500	Vrms	RH=60%, 1min
Operating Te	emperature	Торг	-40 to 85	°C	
Storage Tem	perature	T _{stg}	-40 to 100	°C	
Pin Soldering	g Temperature	T _{sol}	260	°C	10 sec max.

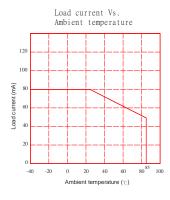
Electrical Characteristics (Ta = 25°C)

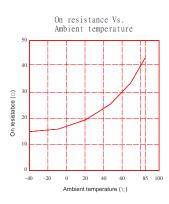
	Item	Symbol	MIN.	TYP.	MAX.	Units	Conditions
	LED Forward Voltage	VF		1.2	1.4	٧	I⊧=10mA
	Operation LED Current	Fon		0.5	3.0	mA	
Input	Recovery LED Current	Foff		0.35	0.5	mA	
	Recovery LED Voltage	V _{Foff}	0.5			٧	
	On-Resistance	Ron		35	50	Ω	I _F =5mA,I _L =100mA, Time to flow is within 1 sec.
Output	Off-State Leakage Current	Leak	0.01	0.02	0.1	uA	V∟=Rating
	Output Capacitance	Cout		3		pF	V∟=0, f=1MHz
Transmis	Turn-On Time	Ton		0.03	0.20	ms	I⊧=5mA, I∟=100mA,
sion	Turn-Off Time	Toff		0.05	0.20	ms	
O I I	I/O Isolation Resistance	R _{I/O}	10 ¹⁰			Ω	DC500V
Coupled	I/O Capacitance	Ci/o		0.8	1.5	pF	f=1MHz

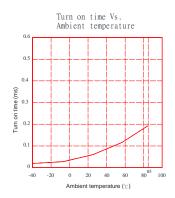
Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value): IF ≥5mA and ≤30mA

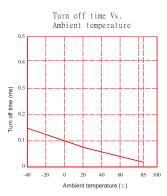


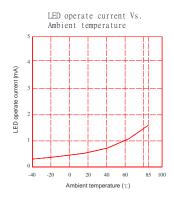
Engineering Data

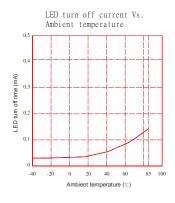


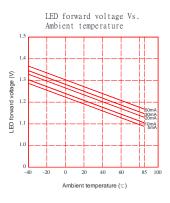


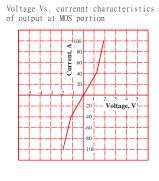


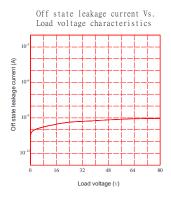


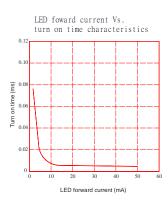


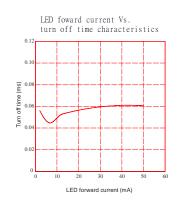


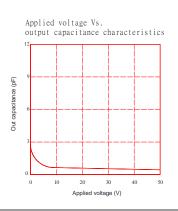












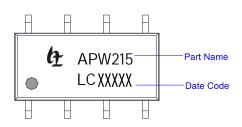
Rev 1.0

Dec,2016



Dimensions and SOP-8 Package Unit: mm

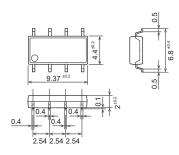
Marking



Lable



Surface mount terminal type

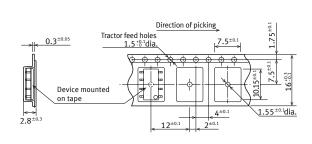


Recommended mounting pad (Top view)

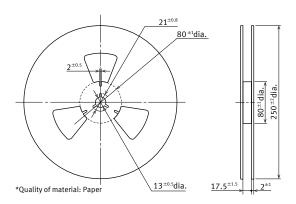


Tape dimensions (tape reel)

Tape dimensions (Unit: mm)



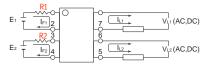
Dimensions of paper tape reel (Unit: mm)





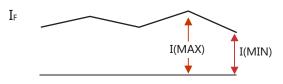
Using Methods

Examples of resistance value to control LED forward current (IF=5mA)



E1 E2	R1 R2(Approx)
3.3V	300 Ω
5.0V	600 Ω
12V	1.9KΩ
24V	4.1K Ω

LED forward current must be more than 5mA, at I(MIN), and less than 30mA, at I(MAX).



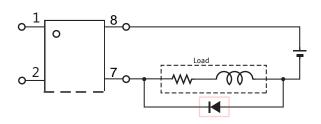
Recommended Operating Conditions

Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value):

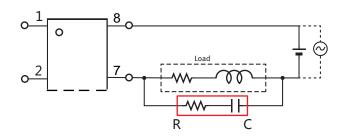
Characteristic	Symbol	Min	Тур.	Max	Unit
Forward current	lF	5.0	7.0	30	mA

Protection Circuit

Clamp diode is connected in parallel with the load. Absorb capacity with external diode.



CR Snubber is connected in parallel with the load. Absorb capacity with buffer capacity.



When adding diodes, buffer circuits (C-R), and other protections, they need to be installed near the MOS RELAY to be effective. Adding protection elements may result in a slow reset time, so adjust them according to the actual situation before use.

Note: When developing designs using this product, perform the expected performance of the equipment under the operating conditions recommended by the guidelines in this document. Continuous use under heavy loads (including, but not limited to, the application of high temperatures/current/voltage and significant changes in temperature, etc.) may result in deterioration of the reliability of this product.



RESTRICTIONS ON PRODUCT USE

APSEMI Co. and its subsidiaries and affiliates (collectively "APSEMI") reserve the right to make changes to all information contained in this document relating to hardware, software, and systems (collectively "Products").

No information in this document may be reproduced without the prior written permission of APSEMI. Even with APSEMI's written permission, this document may only be reproduced if it is guaranteed to be unaltered or missing.

APSEMI assumes no responsibility for unintended uses of the product:

Unintended uses include, but are not limited to, equipment used in nuclear facilities, equipment used in the aerospace industry, medical equipment, automobiles, trains, ships, and other transportation equipment, traffic signaling equipment, equipment used for the control of combustion or explosions, safety devices, elevators and escalators, equipment used in electrical power-related applications, and equipment used in financial-related applications.

APSEMI assumes no responsibility for the product if you use it for any purpose other than the specific purpose described in this document.

- The information contained herein is provided only as a guide for the use of the product.
 APSEMI assumes no responsibility for infringement of third party patents or any other intellectual property rights that may result from the use of the product. This document does not grant any license, express or implied, estoppel or otherwise, to any intellectual property.
- GaAs (Gallium Arsenide) is used in products and is harmful to humans. Inadvertent ingestion or absorption of GaAs can harm the human body, so handle the product with care and do not break, cut, crush, grind, chemically dissolve, or otherwise expose GaAs in the product.
- •Please be aware of environmental issues and use products in compliance with all applicable laws and regulations governing the inclusion or use of controlled substances, including but not limited to the EU RoHS Directive. APSEMI assumes no responsibility for damages or losses resulting from non-compliance with applicable laws and regulations.